

**ABSTRACT**

The present invention relates to a polishing pad. In particular, the polishing pad of the present invention can include a window. The polishing pad of the present invention can be useful for polishing articles and can be especially useful for chemical mechanical polishing or planarization of a microelectronic device, such as a semiconductor wafer. The window of the polishing pad is at least partially transparent and thus, can be particularly useful with polishing or planarizing tools that are equipped with through-the-platen wafer metrology.